

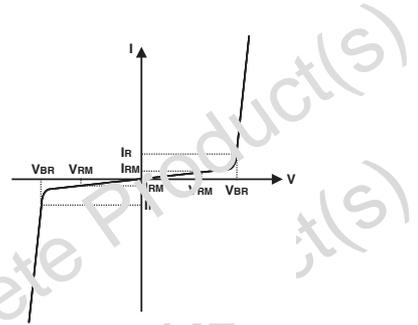
1 Characteristics

Table 1. Absolute ratings (limiting values)

Symbol	Parameter and test conditions	Value	Unit
T_j	Maximum junction temperature	125	°C
T_{op}	Operating temperature range	- 40 to + 85	°C
T_{stg}	Storage temperature range	- 55 to + 150	°C

Table 2. Electrical characteristics ($T_{amb} = 25^\circ\text{C}$)

Symbol	Parameter
V_{BR}	Breakdown voltage
I_{RM}	Leakage current @ V_{RM}
V_{RM}	Stand-off voltage
C_{line}	Input capacitance per line



Symbol	Test conditions	Tolerance	Min.	Typ.	Max.	Unit
V_{BR}	$I_R = 1\text{ mA}$		6		9	V
I_{RM}	$V_{RM} = 5\text{ V per line}$				1	μA
R_1, R_2	$I = 10\text{ mA}$	$\pm 5\%$		33		Ω
R_3	$I = 1\text{ mA}$	$\pm 5\%$		1.5		$\text{k}\Omega$
C_{line}	@ 0 V			30		pF
Matching	Serial resistance matching			1		%

Figure 1. S21 (dB) attenuation measurement Figure 2. Analog crosstalk measurements

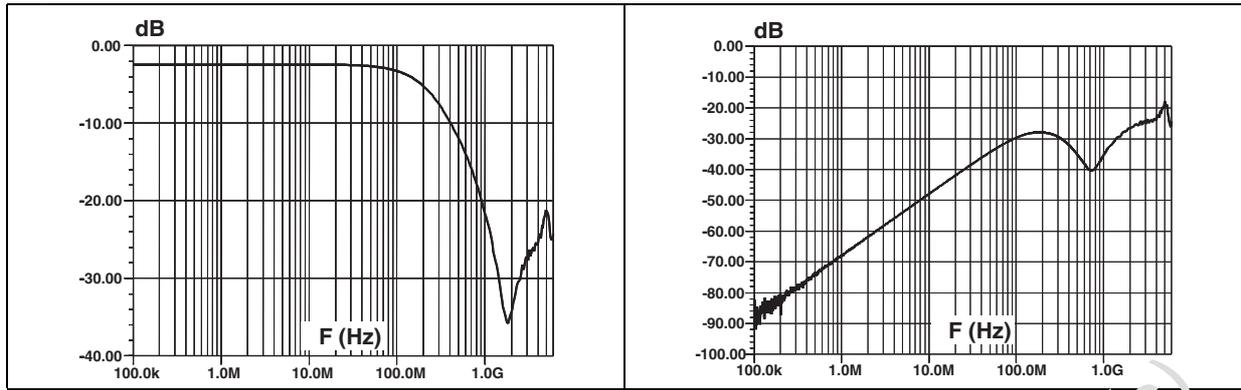


Figure 3. ESD response to IEC 61000-4-2 (+15 kV air discharge) on one input (Vin) and on one output (Vout)

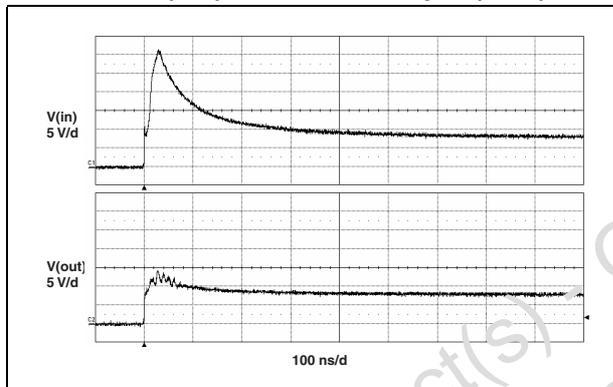


Figure 4. ESD response to IEC 61000-4-2 (-15 kV air discharge) on one input (Vin) and on one output (Vout)

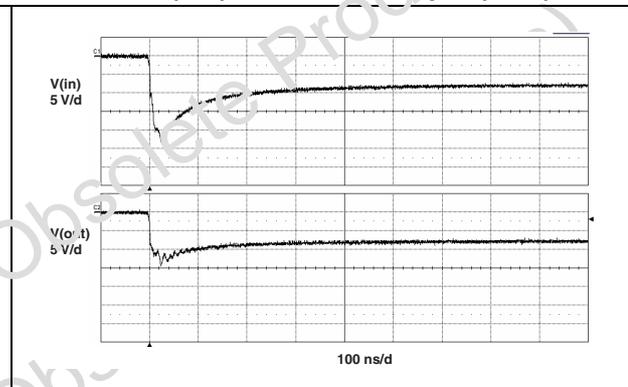


Figure 5. Junction capacitance versus reverse voltage applied

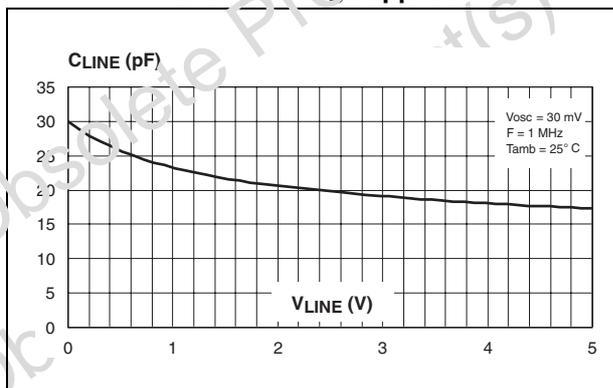


Figure 6. Aplac model device structure

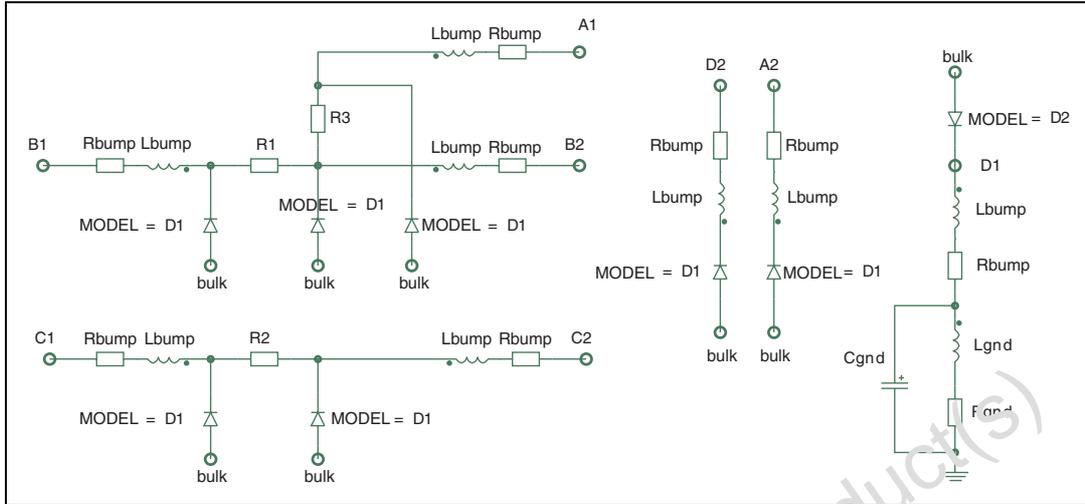
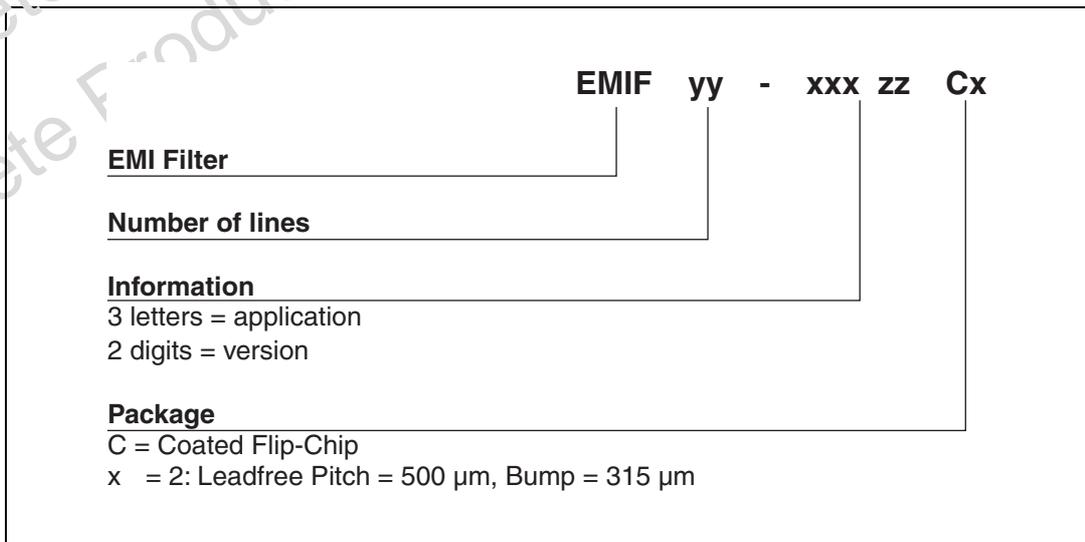


Figure 7. Aplac model parameters

<p> aplacvar R1 33 aplacvar R2 33 aplacvar R3 1.5k aplacvar Cz_D1 15pF aplacvar Rs_D1 1 aplacvar Cz_D2 300pF aplacvar Rs_D2 0.3 aplacvar Lgnd 10 JpH aplacvar Rgnd 10 Ωm aplacvar Cgnd 0.4pF aplacvar Lbump 50pH aplacvar Rbump 20m </p>	<p> Diode D1 BV=7 IBV=1m CJO=Cz_d1 M=0.3333 RS=Rs_d1 VJ=0.6 TT=100n </p>	<p> Diode D2 BV=7 IBV=1m CJO=Cz_d2 M=0.3333 RS=Rs_d2 VJ=0.6 TT=100n </p>
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2 Ordering information scheme



3 Package information

Figure 8. Flip-Chip package dimensions

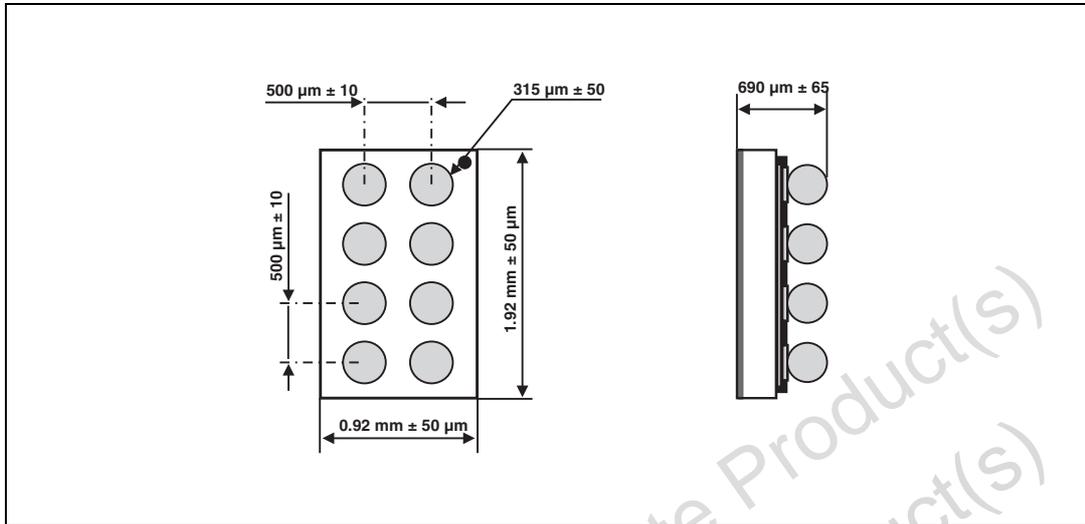


Figure 9. Foot print recommendations Figure 10. Marking

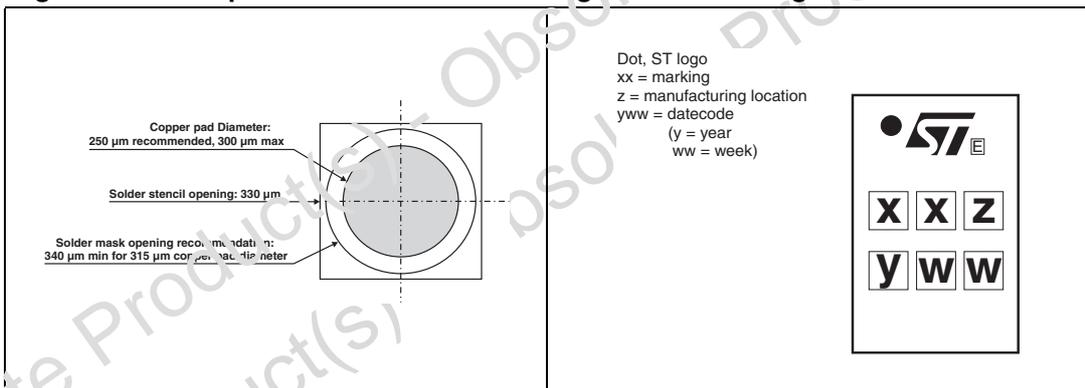
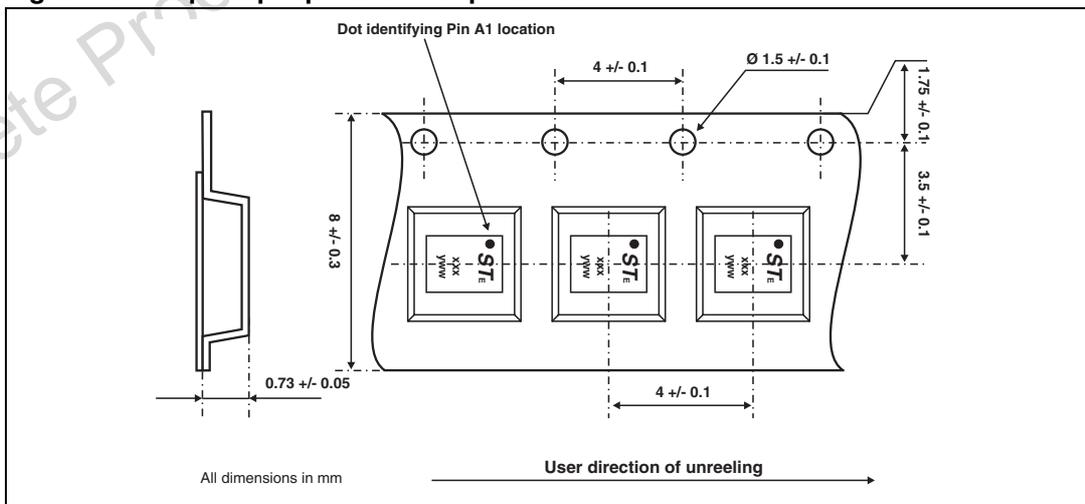


Figure 11. Flip-Chip tape and reel specification



Note: More packing information is available in the application notes

AN1235: "Flip-Chip: Package description and recommendations for use"

AN1751: "EMI Filters: Recommendations and measurements"

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

4 Ordering information

Ordering code	Marking	Package	Weight	Base qty	Delivery mode
EMIF02-USB05C2	GV	Flip-Chip	2.7 mg	5000	Tape and reel 7"

5 Revision history

Date	Revision	Changes
14-Mar-2005	1	Initial release.
13-Nov-2006	2	Reformatted to current standards. Modified functional diagram on page 1 to show connections. Updated Aplac model information.

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